

Connector for miniSD™ Card

SCJB Series

Low-profile type in 2.15mm and 2.2mm thicknesses features the high reliability contact structure.

For SD Memory Card

For miniSD™ Card

For microSD™ Card

For RS-MMC™

For W-SIM™

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

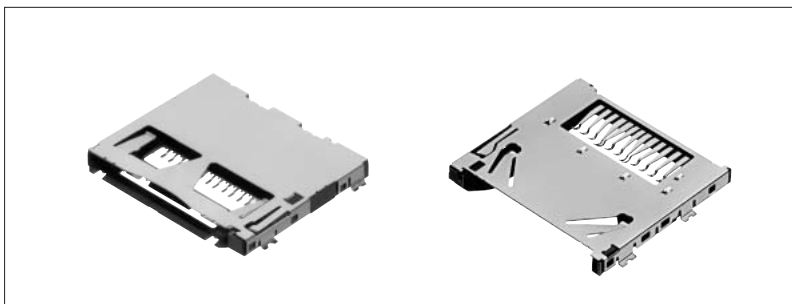
For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module



RoHS applicable



Features

- To defend from loss when memory card was ejected, half-lock structure is adopted.
- Media detection switch adopts highly reliable contact structure with sliding at ON/OFF. Media detection switch surely detects timing when media are inserted.
- Highly shock-resistant robust guard lock.
- Compact size and low-profile.

Applications

- Digital cameras, digital camcorders, mobile phones, personal digital assistants, PCs and etc.

Typical Specifications

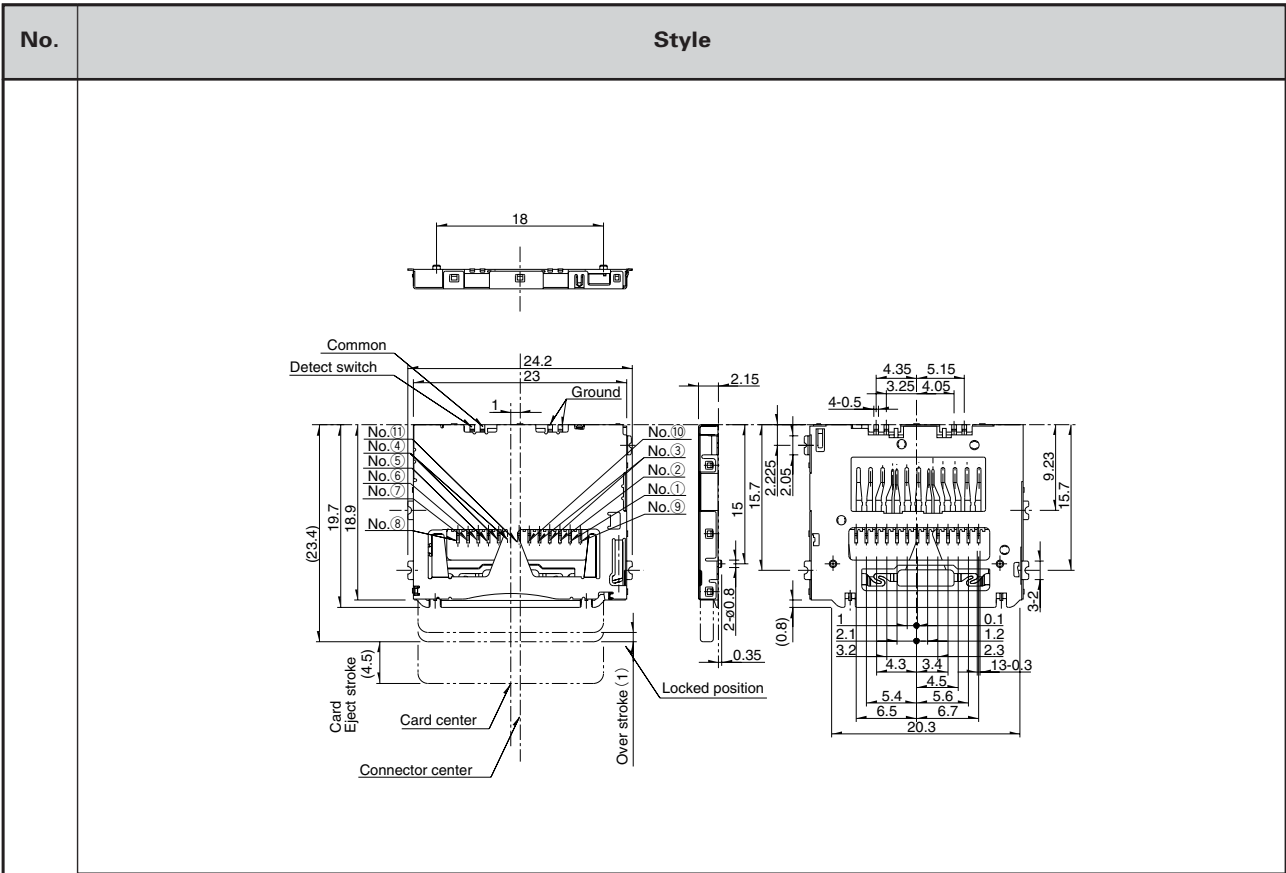
Items		Specifications	
Structure	Applicable media	miniSD™ Card	
	Mounting method	Surface mounting type	
	Mounting system	Standard mount/Reverse mount	
	Media ejection structure	Push-push type	
Performance	Operating temperature range	-25°C to +70°C	
	Voltage proof	500V AC 1 minute	
	Insulation resistance (Initial)	1,000MΩ min.	
	Contact resistance (Initial)	Connector contacts	100mΩ max.
		Detection switch	500mΩ max.
Mating and unmating cycle	10,000 cycles		

Products List

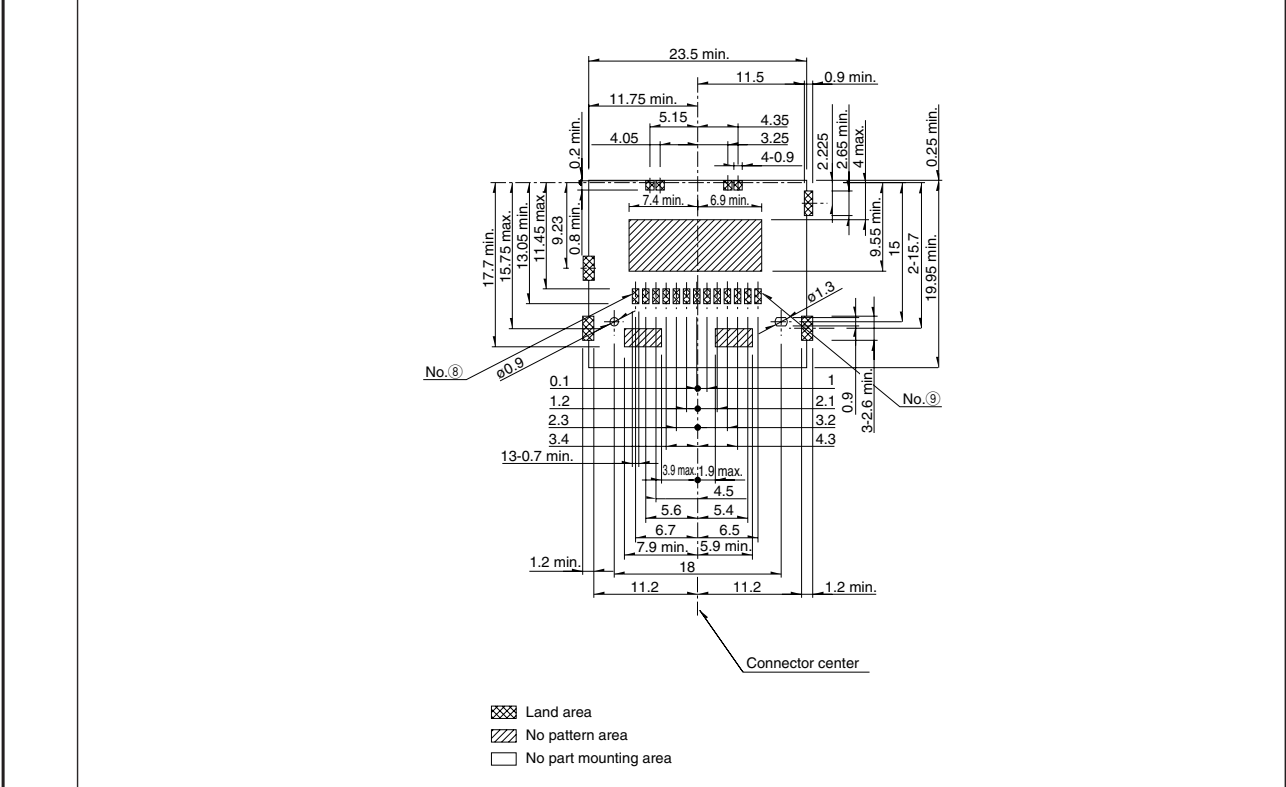
Media ejection structure	Mounting system	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	0	Taping	SCJB1B0301	1
	Reverse mount			SCJB2B0201	2

Dimensions
Standard mount

Unit:mm



1 PC board mounting hole dimensions (Viewed from the mounting face side)

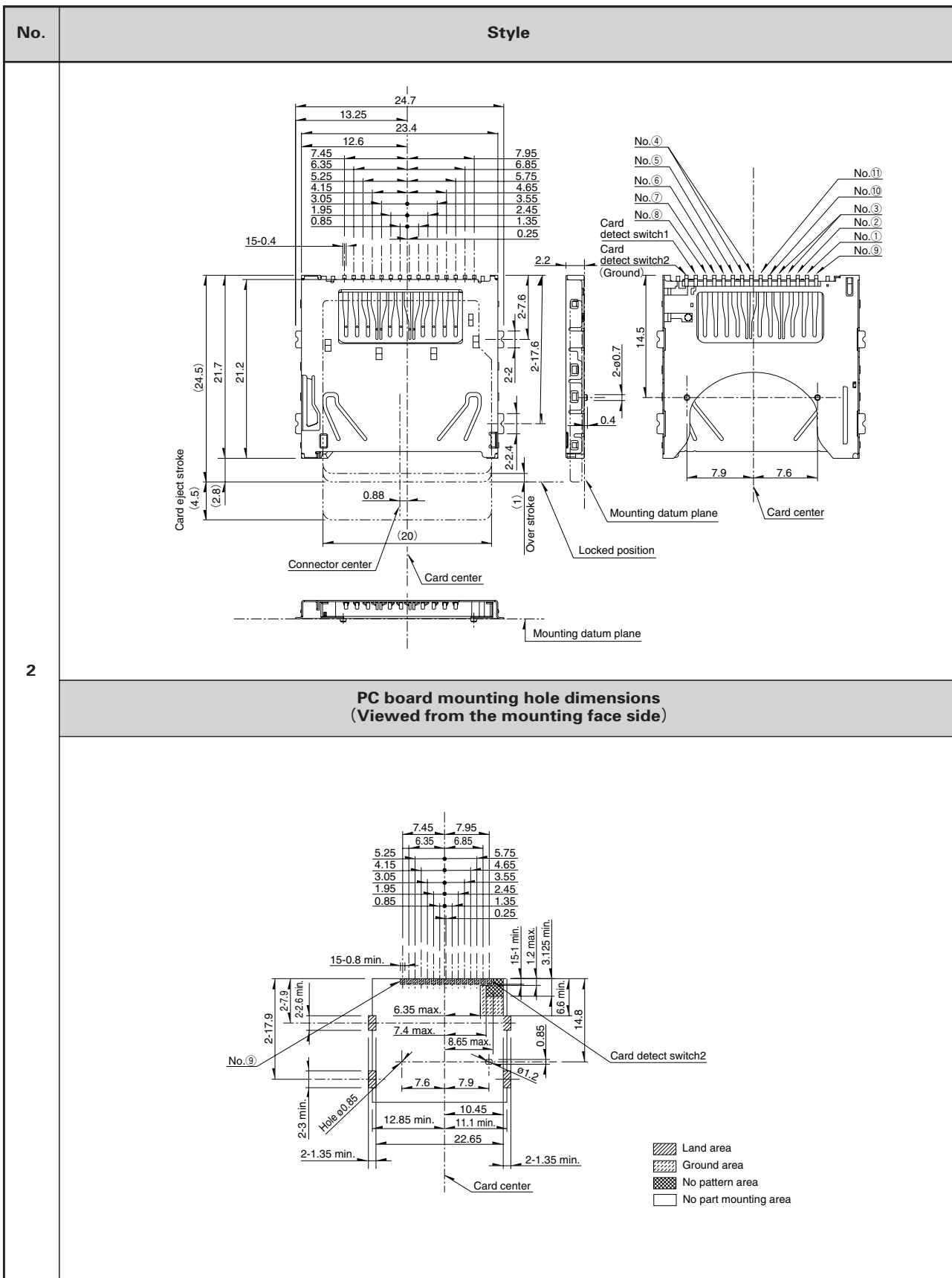


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Dimensions
Reverse mount

Unit:mm

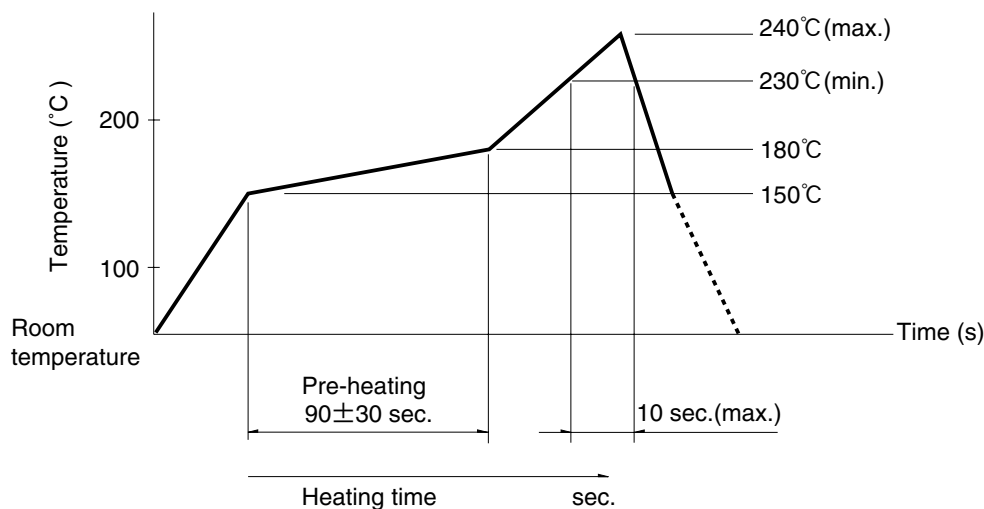
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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



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Cautions

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. When soldering, do not use water soluble flux because this may corrode the product.
3. Regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
4. As PC board warping may alter characteristics, please take this into consideration when designing pattern and layout.
5. This product has been designed and manufactured for applications to ordinary electronic equipment and devices such as the AV equipment, electric home applications, office machines and communications equipment, consequently, when employing these products for applications requiring a high degree of safety and reliability such as the medical equipment, aviation and aircraft equipment, space equipment and burglar alarm equipment, the using manufacturers will please thoroughly study the proprieties of these products for the planned applications.
6. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.